HLMP-PB00-N0000/HLMP-PM00-N0000 HLMP-QB00-S0000/HLMP-QM00-S0000



Subminiature Blue and Green InGaN LED Lamps

Data Sheet



Description

Flat Top Package

The HLMP-Pxxx flat top lamps use an untinted, nondiffused, truncated lens to provide a wide radiation pattern that is necessary for use in backlighting applications. The flat top lamps are also ideal for use as emitters in light pipe applications.

Dome Package

The HLMP-Qxxx dome lamps use an untinted, nondiffused lens to provide a high luminous intensity within a narrow radiation pattern.

Lead Configurations

All these devices are made by encapsulating LED chip on axial lead frames to form molded epoxy subminiature lamps. A variety of package configuration options is available. These include special surface mount lead configurations, gull wing, yoke lead, or Z-bend. Right angle lead bend at 2.54 mm (0.100 inch) and 5.08 mm (0.200 inch) center spacing are available for through hole mounting. For more information refer to Standard SMT and Through Hole Lead Bend Options for Subminiature Lamps data sheet.

Features

- Subminiature flat top package Ideal for backlighting and light piping applications
- Subminiature dome package Nondiffused dome for high brightness
- Colors: 468 nm blue, 525 nm green
- Ideal for space limited applications
- Axial leads
- Available with lead configurations for surface mount and through hole PC board mounting

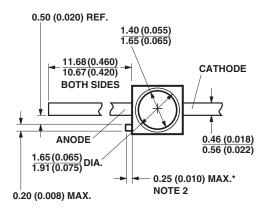
Applications

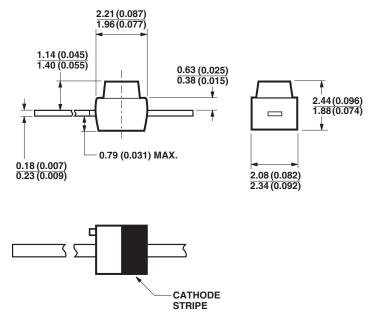
- Consumer
- Industrial
- Computer peripheral
- Communication

CAUTION: HLMP-xB00 and HLMP-xM00 LEDs are Class 2 ESD sensitive. Please observe appropriate precautions during handling and processing. Refer to Avago Application Note AN-1142 for additional details.

Package Dimensions

(A) Flat Top Lamps





NOTES:

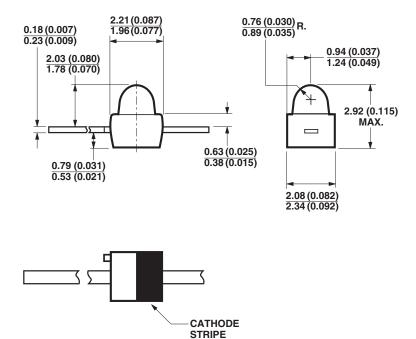
- 1. ALL DIMENSIONS ARE IN MILLIMETERS (INCHES). 2. PROTRUDING SUPPORT TAB IS CONNECTED TO CATHODE LEAD.

* REFER TO FIGURE 1 FOR DESIGN CONCERNS.

Package Dimensions

B) Domed Lamps

0.50 (0.020) REF. 11.68 (0.460) BOTH SIDES ANODE 1.65 (0.065) 1.91 (0.075) DIA. 0.20 (0.008) MAX. CATHODE 0.46 (0.018) 0.56 (0.022) 0.25 (0.010) MAX.*



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS (INCHES).

2. PROTRUDING SUPPORT TAB IS CONNECTED TO CATHODE LEAD.

* REFER TO FIGURE 1 FOR DESIGN CONCERNS.

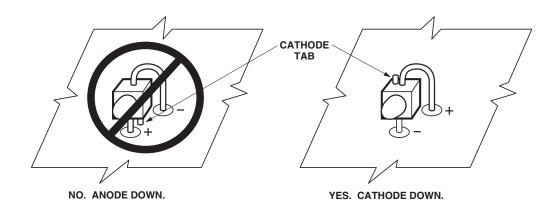
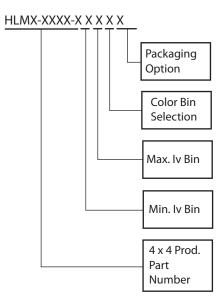


Figure 1. Proper right angle mounting to a PC board to prevent protruding cathode tab from shorting to anode connection.

Device Selection Guide

Part Number	Color	Viewing Angle 2 $\theta_{1/2}$	Package Description	Package Outline
HLMP-PB00-N0000	Blue	85°	Flat Top, Nondiffused, Untinted	А
HLMP-PM00-N0000	Green			
HLMP-QB00-S0000	Blue	12°	Domed, Nondiffused, Untinted	В
HLMP-QM00-S0000	Green			

Ordering Information



Absolute Maximum Ratings at $T_A\,{=}\,25^\circ C$

90 mA 30 mA 110 mW
110 mW
5 V
-40°C to +85°C
-55°C to +100°C
110°C
260°C for 5 seconds
260°C for 20 seconds

Note:

1. Derate linearly as shown in Figure 5.

Optical Characteristics at $T_A=25^\circ C$

	Luminous Intensity Iv (mcd) @ I _F = 20 mA		Color, Peak Wavelength	Dominant Wavelength	Spectral Halfwidth	Viewing Angle 2 $\theta_{1/2}$	Luminous
Part Number	Min.	Тур.	λ _{ΡΕΑΚ} (nm) Тур.	λ _d (nm) Typ.	- λ _{1/2} (nm) Тур.	Degrees Typ.	Efficacy ղ v (lm/W)
HLMP-PB00-N0000	25	60	470	468	26	85	70
HLMP-PM00-N0000	25	200	523	525	36	85	500
HLMP-QB00-S0000	160	290	470	468	26	12	70
HLMP-QM00-S0000	160	690	523	525	36	12	500

Electrical Characteristics at $T_A = 25^\circ C$

	Forward Voltage V _F (Volts) @ I _F = 20 mA		Reverse Breakdown V _R (Volts) @ I _R = 100 μA	Capacitance C (pF), V _F = 0, f = 1 MHz	Thermal Resistance Rθ _{J-PIN} (°C/W)	
Part Number	Тур.	Max.	Min.	Тур.	Тур.	
HLMP-PB00-N0000	3.7	4.1	5	52	170	
HLMP-PM00-N0000	3.7	4.1	5	52	170	
HLMP-QB00-S0000	3.7	4.1	5	52	170	
HLMP-QM00-S0000	3.7	4.1	5	52	170	

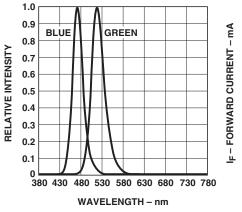


Figure 2. Relative intensity vs. wavelength.

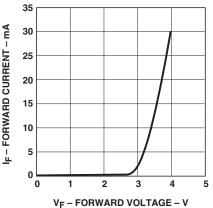


Figure 3. Forward current vs. forward voltage.

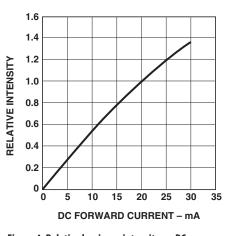
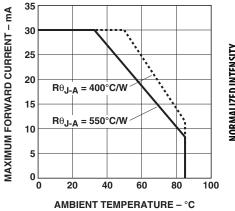


Figure 4. Relative luminous intensity vs. DC forward current.



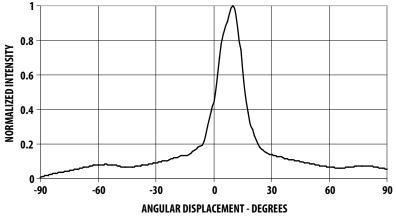


Figure 5. Maximum forward current vs. ambient temperature. Derating based on T_JMAX = 110½C.

Figure 6. Relative luminous intensity vs. angular displacement for HLMP-Qxxx.

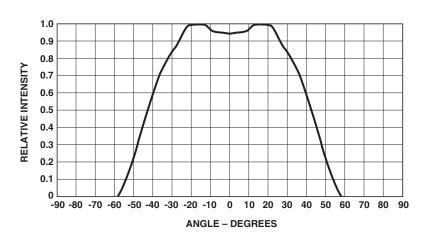


Figure 7. Relative luminous intensity vs. angular displacement for HLMP-Pxxx.

Intensity Bin limits

Min.	Max.
25	50
40	80
63	125
100	200
160	320
250	500
400	800
630	1250
1000	2000
1600	3200
2500	5000
	25 40 63 100 160 250 400 630 1000 1600

Color Bin limits

Package	Bin	Min.	Max.		
Blue	0	Full Distri	Full Distribution		
	1	460	464		
	2	464	468		
	3	468	472		
	4	472	476		
	5	476	480		
	6	480	484		
Green	0	Full Distri	bution		
	3	520	525		
	4	525	530		
	5	530	535		
	6	535	540		

Tolerance of each bin limit = ± 2 nm.

Mechanical Option

00	Straight Leads.	Bulk Packaging.	, Quantity of 500 Part	s
00	Straight Leads,	built i ucituging,	, Quantity of 500 runt	5

- 11 Gull Wing Leads, 12 mm Tape on 7 in. Dia. Reel, 1500 Parts per Reel
- Gull Wing Lead, Bulk Packaging, Quantity of 500 Parts 12
- 14 Gull Wing Leads, 12 mm Tape on 13 in. Dia. Reel, 6000 Parts per Reel
- 21 Yoke Leads, 12 mm Tape on 7 in. Dia. Reel, 1500 Parts per Reel

22 Yoke Leads, Bulk Packaging, Quantity of 500 Parts

24 Yoke Leads, 12 mm Tape on 13 in. Dia. Reel, 6000 Parts per Reel

31 Z-Bend Leads, 12 mm Tape on 7 in. Dia. Reel, 1500 Parts per Reel

32 Z-Bend Leads, Bulk Packaging, Quantity of 500 Parts

34 Z-Bend Leads, 12 mm Tape on 13 in. Dia. Reel, 6000 Parts per Reel

Note:

All Categories are established for classification of products. Products may not be available in all categories. Please contact your local Avago representative for further clarification/information.

For product information and a complete list of distributors, please go to our website: www.avagotech.com

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